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**Weak antilocalization in  $\text{Bi}_{2-x}\text{In}_x\text{Te}_3$  single crystals** HANG CHI, QIANG LI, Brookhaven Natl Lab, CTIRAD UHER, University of Michigan —  $\text{Bi}_2\text{Te}_3$  has recently been identified as one of the most promising systems with which to realize a three-dimensional topological insulator. However, the bulk, stoichiometric  $\text{Bi}_2\text{Te}_3$  single crystals often exhibit  $p$ -type metallic electrical conduction due to the  $\text{Bi}_{\text{Te}}$ -type antisite defects, which overshadows the contribution of surface states. We have established that, upon group III (indium and/or thallium) doping, the Fermi level of  $\text{Bi}_2\text{Te}_3$  can be lifted from the valence band into the band gap, and eventually shifted into the conduction band. Such doping progressively changes the electrical conduction of  $\text{Bi}_{2-x}\text{A}_x\text{Te}_3$  ( $\text{A} = \text{In}, \text{Tl}$ , and  $x = 0 - 0.30$ ) single crystals from  $p$ -type to  $n$ -type. This is observed via measurements of both the Hall effect and the Seebeck coefficient performed in the (0001) basal plane in the temperature range of 2 – 300 K. At low levels, the temperature dependent in-plane electrical resistivity maintains its metallic character as the density of holes decreases. Heavier doping content,  $x = 0.20$  (0.10) for In (Tl), drives the electrical resistivity into a prominent non-metallic regime displaying the weak anti-localization type of magnetoresistance at the lowest temperatures for  $\text{Bi}_{1.80}\text{In}_{0.20}\text{Te}_3$ . At the highest concentration, the samples revert back into the metallic state with electron dominated conduction. Thermal conductivity measurements of  $\text{Bi}_{2-x}\text{A}_x\text{Te}_3$  single crystals, as examined by the Debye-Callaway phonon conductivity model, reveal a generally stronger point defect scattering of phonons upon doping.

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